## Tek goes to IEEE

Tek engineers and marketing personnel will converge on New York City next week for the 1967 IEEE (Institute of Electrical and Electronics Engineers) international convention and exhibition March 20-23 with headquarters at the Coliseum and Hilton hotel.

Preceding them will be the arrival of Tek's 50-foot show booth and 21 new Tek products, packed and shipped last week, which will unfold in booths 2C03-2C13 on the second level of the New York Coliseum.

## Products to be shown

Both Tek Beaverton employees and field engineers will be on hand during show hours to acquaint convention attendees with our new products which range from probes and Scope-Mobile carts to portable scopes and digital systems.

The 21 new products, described in Tekweek March 3, include the 454 and R454; 647A/10A2A/11B2A and R647A; 1A5; 1A4; 3L5; 3T2; 568; 230 digital unit; 200-1, 200-2, 205-2 and 205-3 Scope-Mobile carts; C-40 camera; P6047 passive probe and 3200 digital system.

In between booth duty and technical sessions, several Teks will also participate in IEEE meetings and luncheons. Ten Teks will attend the annual IEEE banquet March 22 when Dr. Walter Dyke, Tek board member and president of FEMCOR, will be honored as a new IEEE Fellow. See page 5 for schedule of meetings Teks plan to attend.

## TEKS ATTEND 'IEEE'

Several Tek Engineering personnel will participate in IEEE committee meetings during the 1967 IEEE convention and exhibition in New York March 20-23. The following is a list of sessions Teks will be attending next week:

Bill Walker, Preproduction Engineering manager, and a member of the International Electrotechnical Conference (IEG) will report on IEG oscilloscope standards and the US position to the IEEE subcommittee on oscilloscopes March 21 and to the IEEE committee on high frequency instruments

and measurements March 22. He'll also attend the IEEE Region VI meeting March 21 as president of the Portland IEEE section.

Lang Hedrick, Instrument Engineering manager, will preside as chairman pro-tem of the Electromagnetic Measurements Task Group 6 on March 23, which is working on standards for electromagnetic measurements. He'll also report on the task group's progress at the meeting of EMMcomm subcommittee heads March 24.

Al Zimmerman, IE Sampling project manager, will report briefly on activities of the IEEE subcommittee on pulse techniques at EMMcomm Task Group 6 meeting March 23. Chuck Samuel, Product Manufacturing Test/Final Staff Engineering manager, is chairman of the IEEE subcommittee on oscilloscopes and will preside at the meeting March 21.

Ralph Show, Instrument Engineering staff, will attend the IEEE section editors luncheon meeting March 20. He is editor of the Portland IEEE section's monthly paper, The BEEEP. Ralph will also attend the meeting of the subcommittee on oscilloscopes March 21 and the EMMcomm Task Group 6 meeting March 23.

Most of these meetings, plus all technical sessions, will be held at the New York Hilton during the four-day convention and exhibition.

